PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3938306

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the RECEIVING PARTY DATA previously recorded on Reel 032809 Frame 0058. Assignor(s) hereby confirms the ASSIGNMENT OF ASSIGNOR'S INTEREST.

CONVEYING PARTY DATA

Name	Execution Date
MIN-HUNG LEE	03/26/2014

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. 6
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77
Name:	NATIONAL TAIWAN UNIVERSITY
Street Address:	NO. 1, SEC. 4, ROOSEVELT RD.
Internal Address:	ZHONGZHENG DISTRICT
City:	TAIPEI CITY
State/Country:	TAIWAN
Postal Code:	100

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14245745

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Email: docketing@slatermatsil.com
Correspondent Name: SLATER MATSIL, LLP
Address Line 1: 17950 PRESTON RD, SUITE 1000
Address Line 4: DALLAS, TEXAS 75252

ATTORNEY DOCKET NUMBER:	TSM14-0058
NAME OF SUBMITTER:	MARANDA BREWSTER
SIGNATURE:	/Maranda Brewster/

DATE SIGNED:	06/28/2016
	This document serves as an Oath/Declaration (37 CFR 1.63).

Total Attachments: 5

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source=TSM14-0058 Original Assignment#page4.tif
source=TSM14-0058 New Assignment#page1.tif

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
MIN-HUNG LEE	03/26/2014

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Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
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City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14245745

CORRESPONDENCE DATA

Fax Number:	(972)732-9218
Phone:	972-732-1001
Email:	docketing@slater-matsil.com

Correspondence will be sent via US Mail when the email attempt is unsuccessful.

Correspondent Name:	SLATER & MATSIL, L.L.P.
Address Line 1:	17950 PRESTON ROAD, SUITE 1000
Address Line 4:	DALLAS, TEXAS 75252

ATTORNEY DOCKET NUMBER:	TSM14-0058
NAME OF SUBMITTER:	WENDY SAXBY
Signature:	/Wendy Saxby/

PATENT
REEL: 039185 FRAME: 0908

Date:	05/02/2014

Total Attachments: 1
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RECEIPT INFORMATION

EPAS ID:	PAT2839852
Receipt Date:	05/02/2014

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ATTORNEY DOCKET NO.
TSM14-0058

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, and National Taiwan University (NTU), a university organized and existing under the laws of Taiwan, with its principal office at No. 1, Sec. 4, Roosevelt Rd., Zhongzheng Dist., Taipei City, Taiwan 100, are desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said TSMC and NTU, their successors and assigns, my entire right, title and interest in and to said invention and in to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said TSMC and NTU, as assignees of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to TSMC and NTU, their successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TSMC and NTU, or to their successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignees, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TSMC and NTU, their legal representatives, successors, and assigns to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	TUNNEL MOSFET WITH FERROELECTRIC GATE STACK			
SIGNATURE OF INVENTOR AND NAME	Min-Hung Lee Min-Hung Lee			
DATE	2014/03/26			
RESIDENCE	New Taipei City, TW			

1/2

ATTORNEY DOCKET NO.
TSM14-0058

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, and National Taiwan University (NTU), a university organized and existing under the laws of Taiwan, with its principal office at No. 1, Sec. 4, Roosevelt Rd., Zhongzheng Dist., Taipei City, Taiwan 100, are desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said TSMC and NTU, their successors and assigns, my entire right, title and interest in and to said invention and in to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said TSMC and NTU, as assignees of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to TSMC and NTU, their successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TSMC and NTU, or to their successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignees, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TSMC and NTU, their legal representatives, successors, and assigns to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	TUNNEL MOSFET WITH FERROELECTRIC GATE STACK			
SIGNATURE OF INVENTOR AND NAME	Min-Hung Lee Min-Hung Lee			
DATE	2014/03/26			
RESIDENCE	New Taipei City, TW			